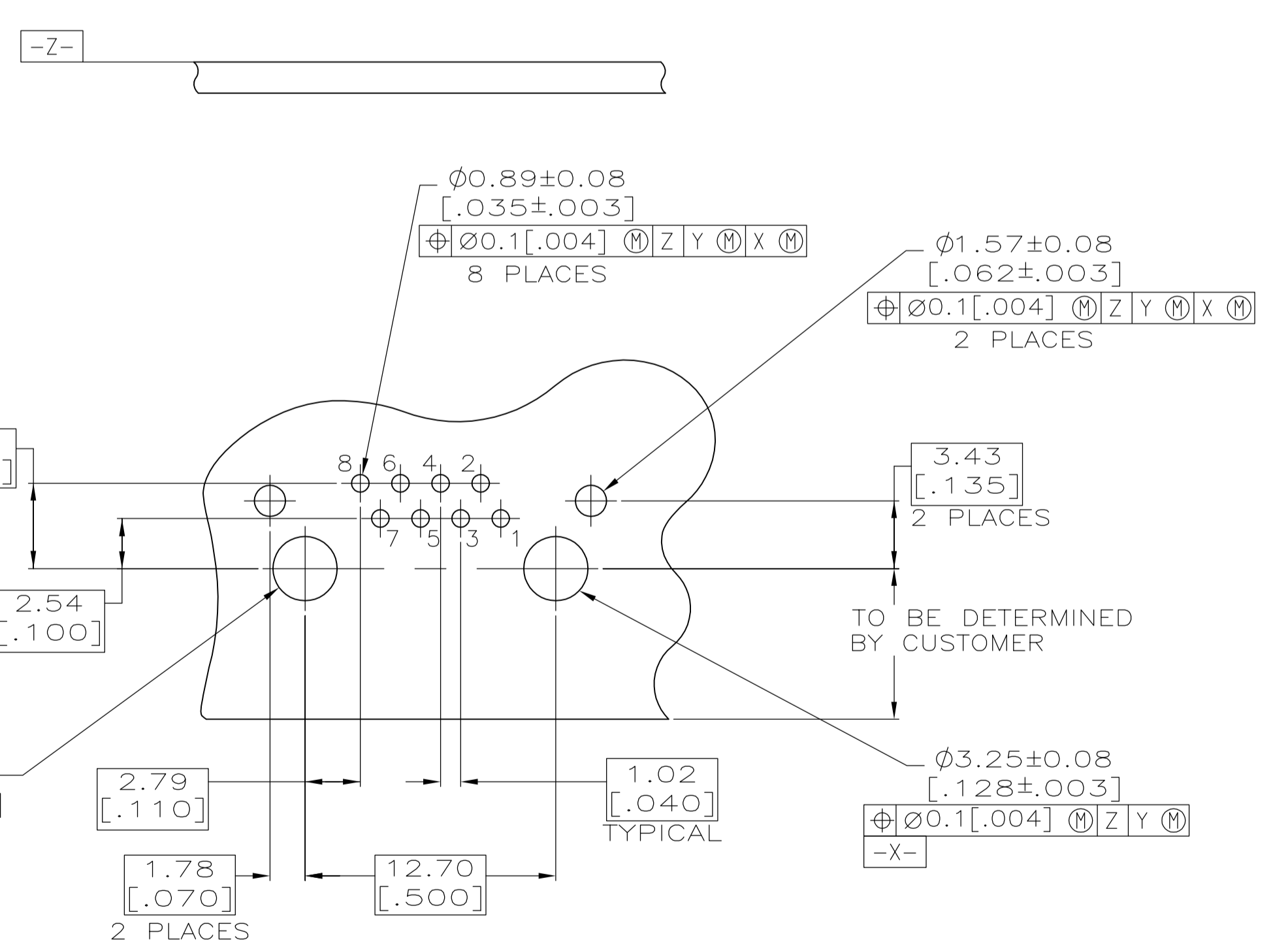
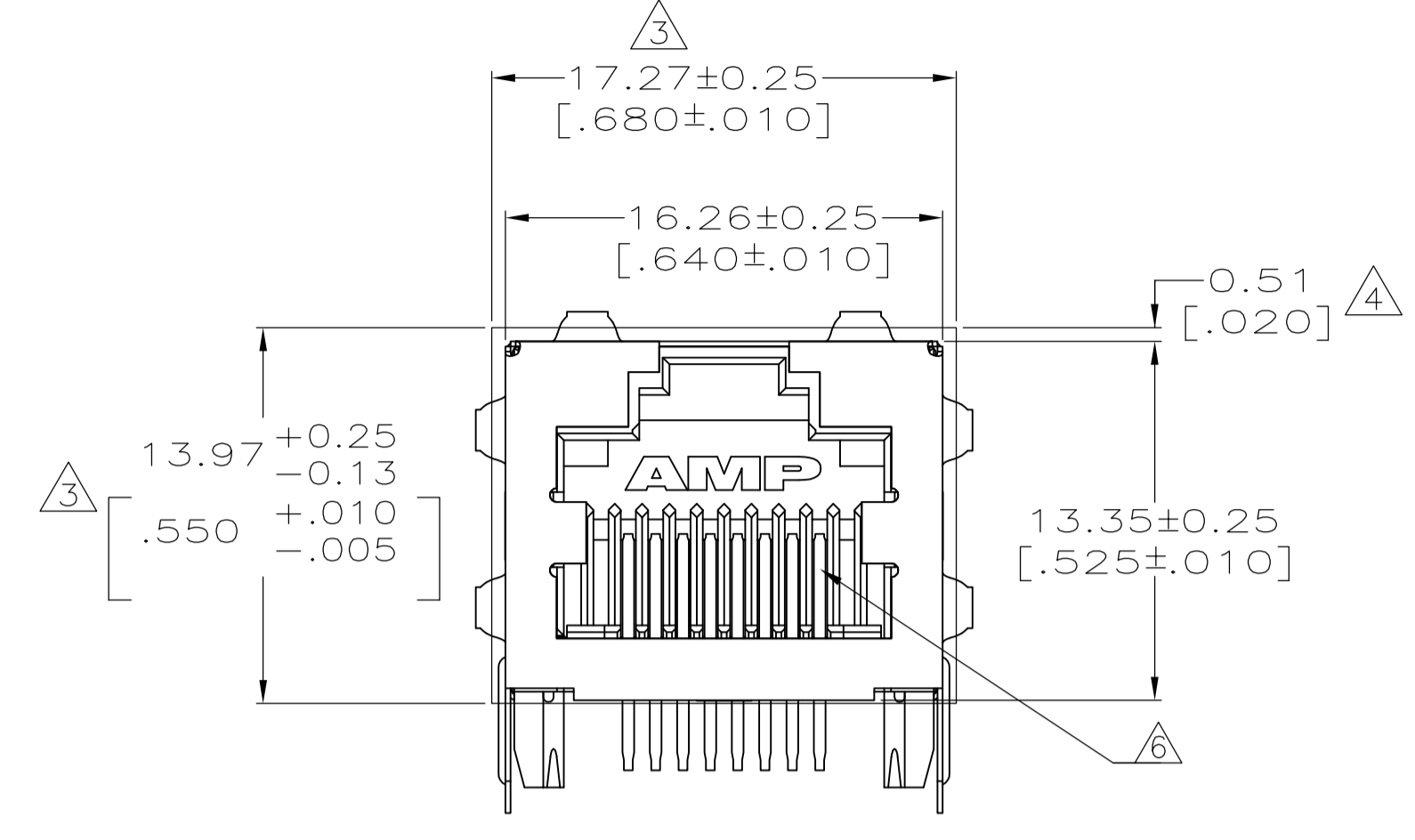
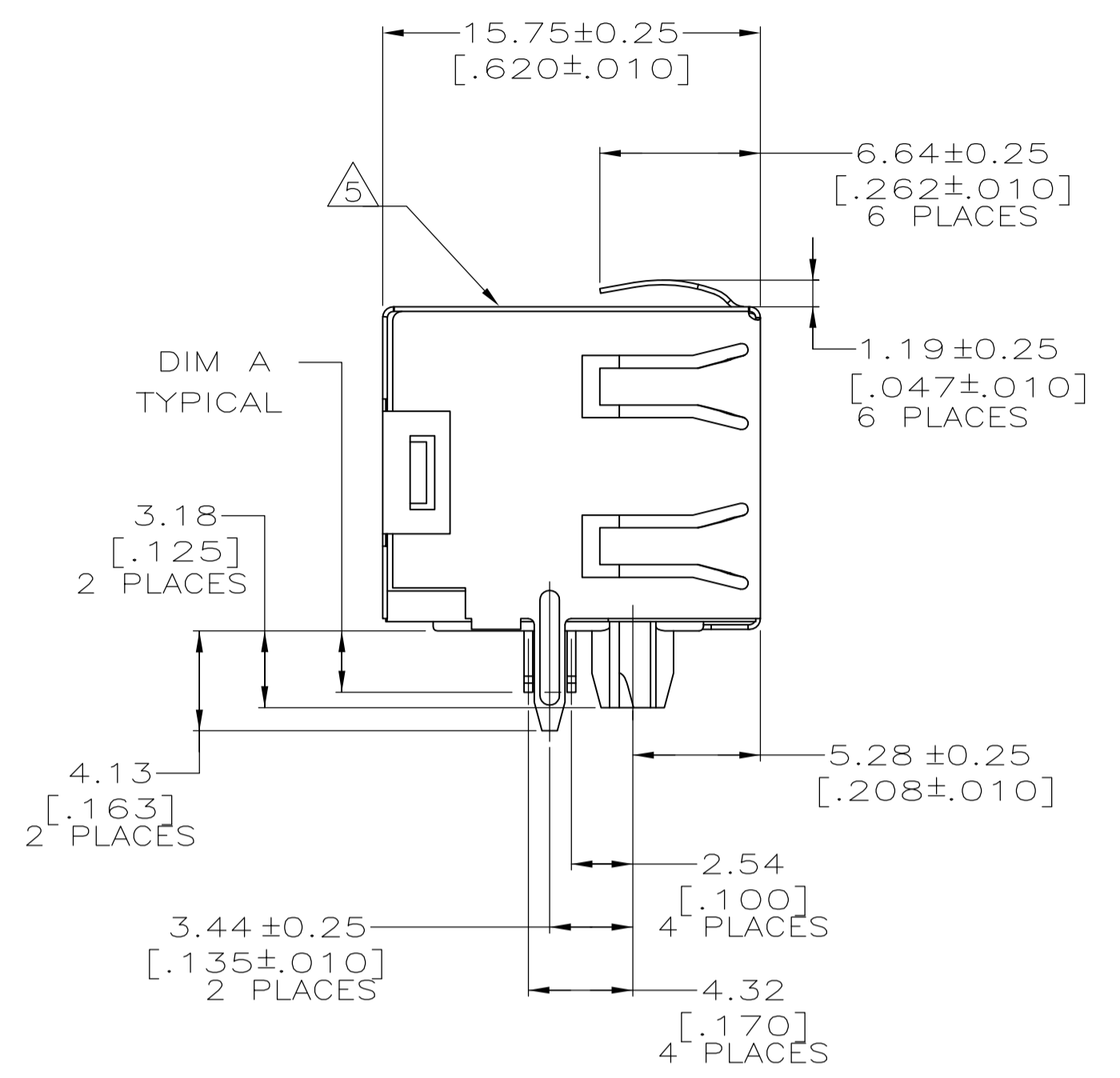


LOC	DIST	REVISIONS		
AA	00	P	LTR	DATE
		B	ECO-15-007496	11MAY2015
				LL SH

- MATERIAL:**
 HOUSING - HIGH TEMPERATURE THERMOPLASTIC, COLOR: BLACK, UL94V-0
 TERMINALS - 0.36[.014] THICK PHOS BRONZE PLATED WITH 3.81 μ m[.000150] MINIMUM THICK MATTE TIN IN SOLDER AREA. 1.27 μ m[.000050] MINIMUM GOLD IN LOCALIZED PLATE AREA. ENTIRE TERMINAL PLATED WITH 1.27 μ m[.000050] MINIMUM THICK NICKEL.
 SHIELD - 0.196[.0077] THICK COPPER ZINC ALLOY PREPLATED WITH 1.27 μ m[.000050] MINIMUM SATIN NICKEL WITH 2.03 μ m[.000080] MINIMUM TIN POST DIPPED ON PCB GROUND TABS.
- JACK CAVITY CONFORMS TO FCC RULES AND REGULATIONS PART 68, SUBPART F.
- SUGGESTED PANEL OPENING DIMENSIONS.**
- SUGGESTED CLEARANCE BETWEEN TOP OF CONNECTOR AND TOP PANEL OPENING.**
- MANUFACTURING DATE CODE:**
 LOCATED APPROX. AS SHOWN.
 FIRST 2 DIGITS = LAST 2 DIGITS OF YEAR.
 NEXT 2 DIGITS = MANUFACTURING WORK WEEK.
 LAST DIGIT = DAY OF WEEK WITH SUNDAY = 1.
- CONTACT AREA LUBRICATED WITH BELLCORE APPROVED LUBRICANT. TECHNICAL REFERENCE GR-1217-CORE ISSUE 1, NOVEMBER 1995.**



SUGGESTED PRINTED CIRCUIT BOARD LAYOUT
 (COMPONENT SIDE)

3.56 [.140]	6	1932219-2
2.54 [.100]	6	1932219-1
DIMENSION A	PANEL GROUNDS	PART NUMBER

THIS DRAWING IS A CONTROLLED DOCUMENT.		DWN D.ZHU 20NOV2008	TE Connectivity	
DIMENSIONS:	TOLERANCES UNLESS OTHERWISE SPECIFIED:	CHK M.LI 20NOV2008	APVD S.YAO 20NOV2008	NAME
mm [INCHES]	0 PLC \pm - 1 PLC \pm - 2 PLC \pm 0.25[.010] 3 PLC \pm - 4 PLC \pm - ANGLES \pm -	PRODUCT SPEC	INVERTED MODULAR JACK ASSEMBLY, 1 X 1, SHIELDED, PANEL GROUND	
MATERIAL	FINISH	APPLICATION SPEC	SIZE	CAGE CODE
SEE TABLE	SEE TABLE	WEIGHT	A1	00779
CUSTOMER DRAWING		SCALE	4:1	SHEET 1 OF 1
		REV	B	